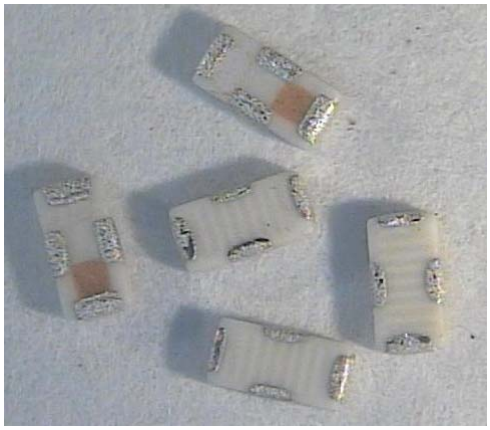
Multilayer Chip Antenna



Features

❖ Monolithic SMD with small, low-profile and light-weight type.

❖ Wide bandwidth

❖ RoHS compliant

Applications

❖2400~2500MHz ISM Band Systems

Specifications

Part Number	Frequency Range (MHz)	Peak Gain (dBi typ.)	Average Gain (dBi typ.)	VSWR	Impedance
AN1608-2440	2400~2480	0.5 (XZ-total)	-2.0 (XZ-total)	3 max.	50 Ω

(*Electrical specification is defined by the measurement of Scenario#1)

Q'ty/Reel (pcs) : 4,000 pcs

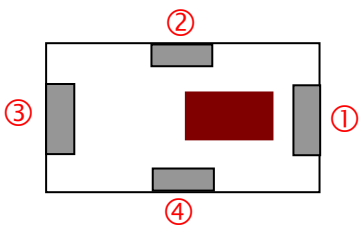
Operating Temperature Range : -40 ~ +85 °C

Storage Temperature Range : -40 ~ +85 °C

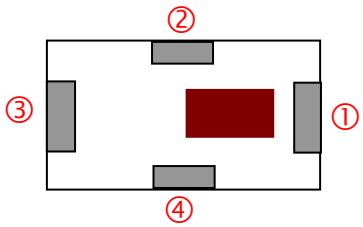
Storage Period : 12 months max.

Power Capacity : 2W max.

Terminal Configuration



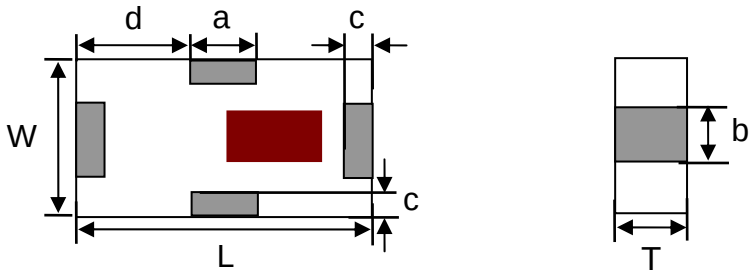
Scenario#1: Antenna on the edge side of PCBA			
No.	Terminal Name	No.	Terminal Name
①	Feeding Point	③	NC
②	GND	④	GND



Scenario#2: Antenna on the corner of PCBA			
No.	Terminal Name	No.	Terminal Name
①	Feeding Point	③	NC
②	NC	④	NC

Dimensions and Recommended PC Board Pattern

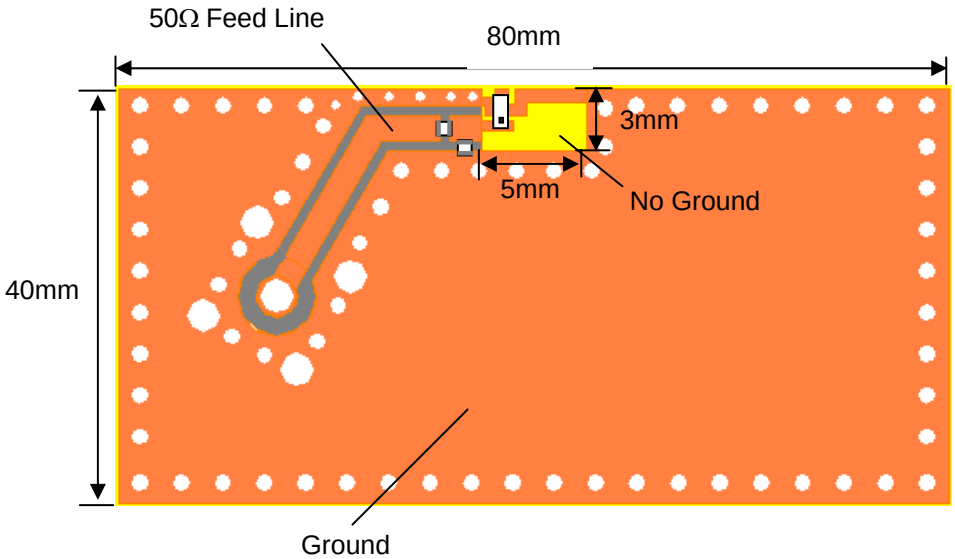
Unit : mm



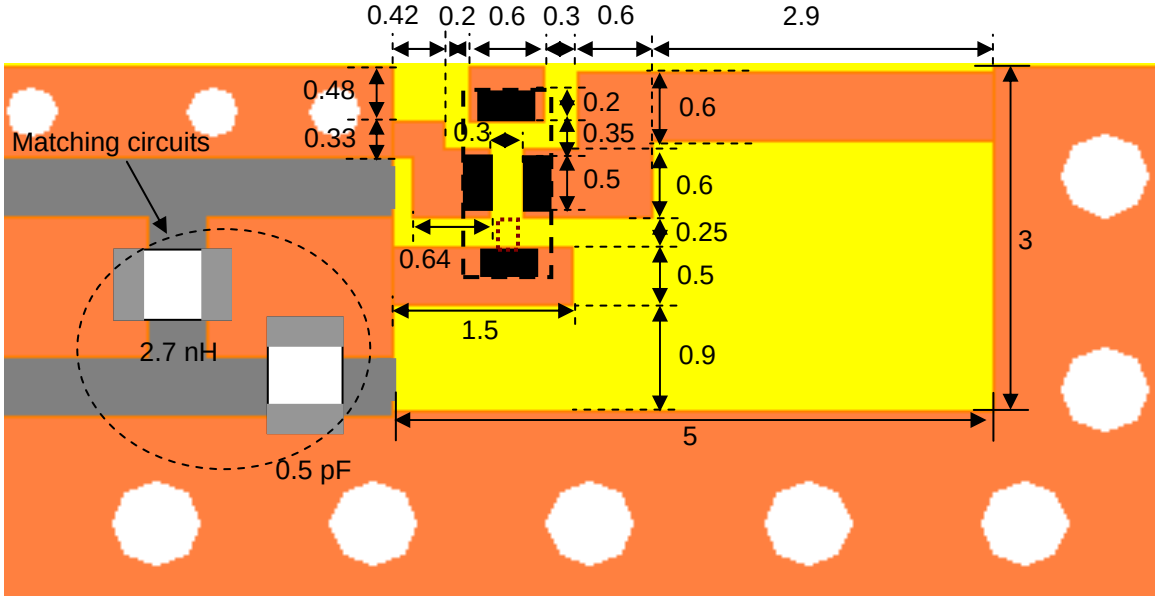
Mark	L	W	T	a	b	c	d
Dimensions	1.6 ± 0.1	0.8 ± 0.1	0.4 ± 0.1	0.5± 0.1	0.5± 0.1	0.2 ± 0.05	0.55 ± 0.1

Typical Electrical Characteristics for Scenario#1 (T=25°C)

❖Test Board-Scenario#1



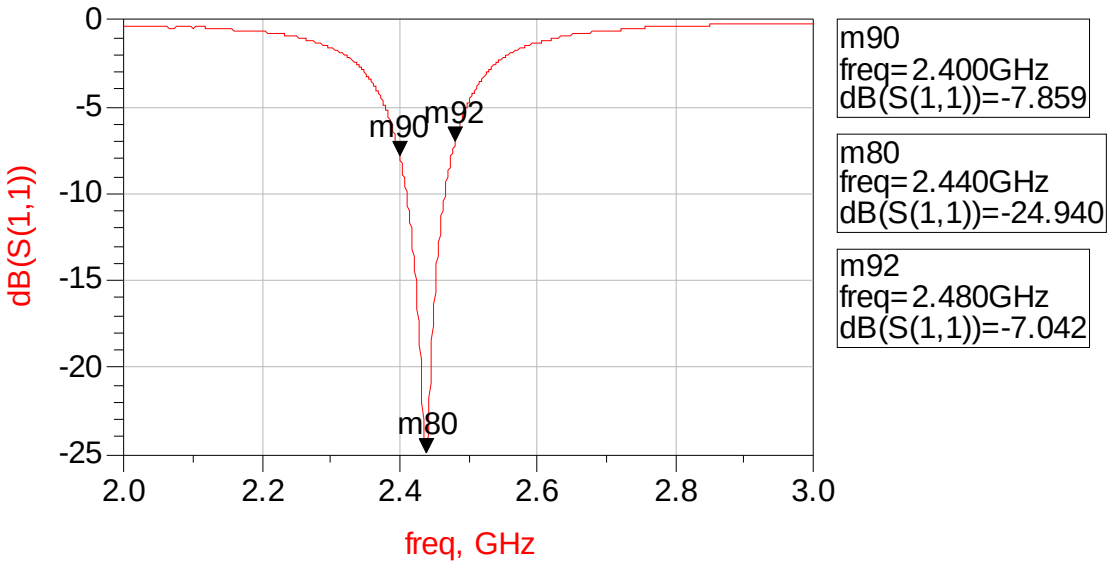
❖Antenna Footprint With matching- Scenario#1 (Unit in mm)



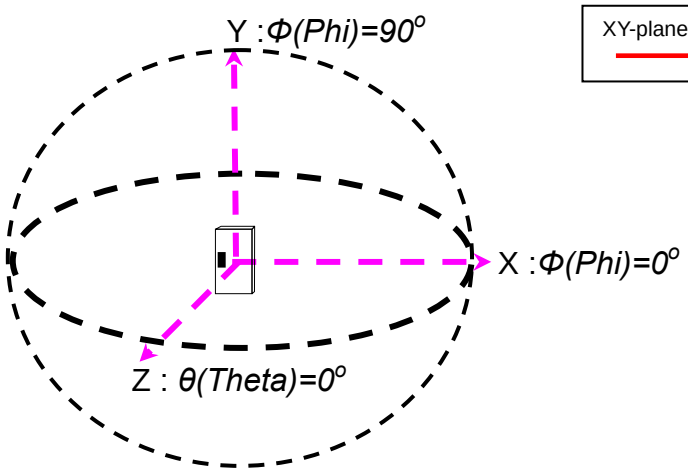
(Matching circuit and component values will be different, depending on PCB layout)

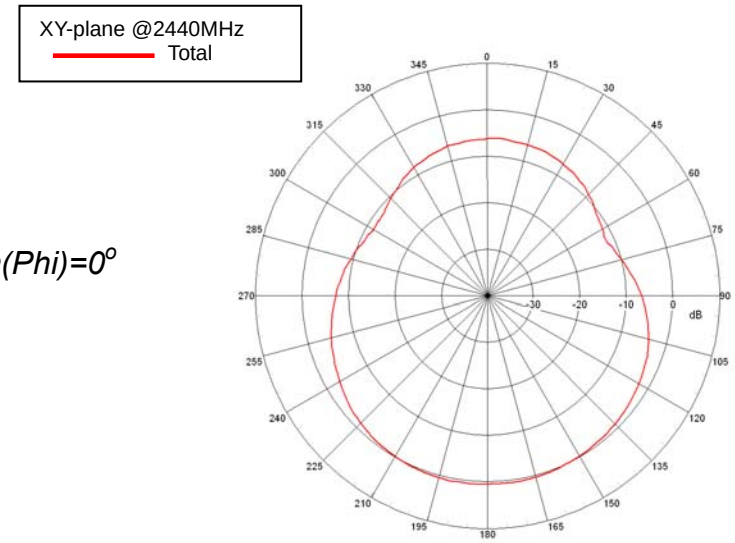
*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

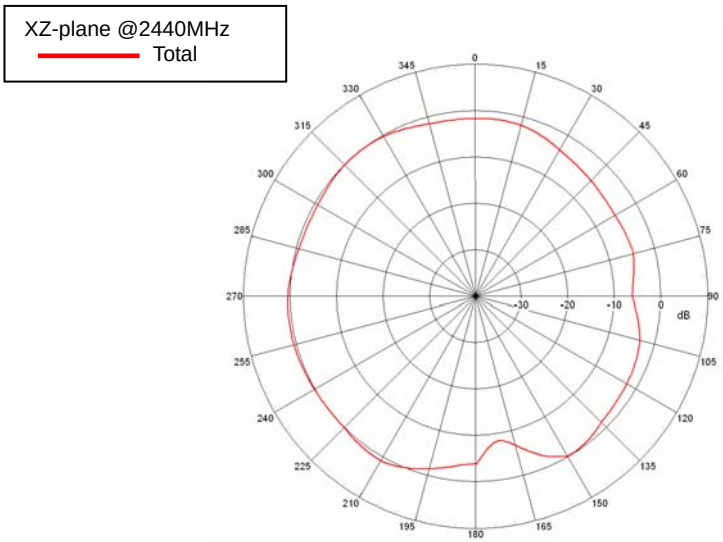
❖Return Loss (with matching)- Scenario#1

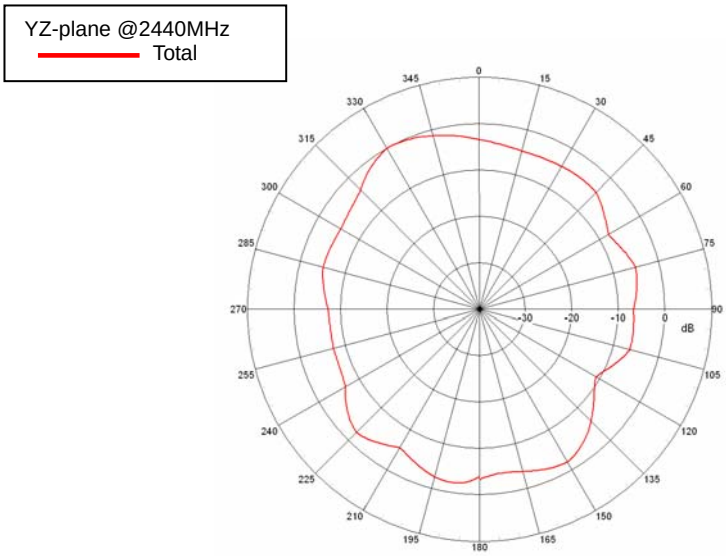


❖Radiation Patterns- Scenario#1 (Antenna Efficiency: 50 %)



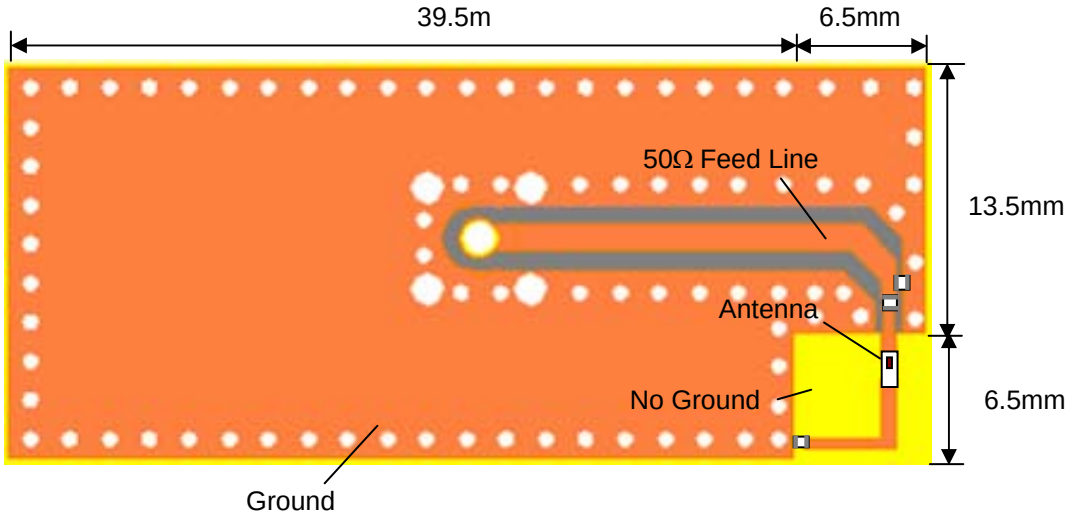




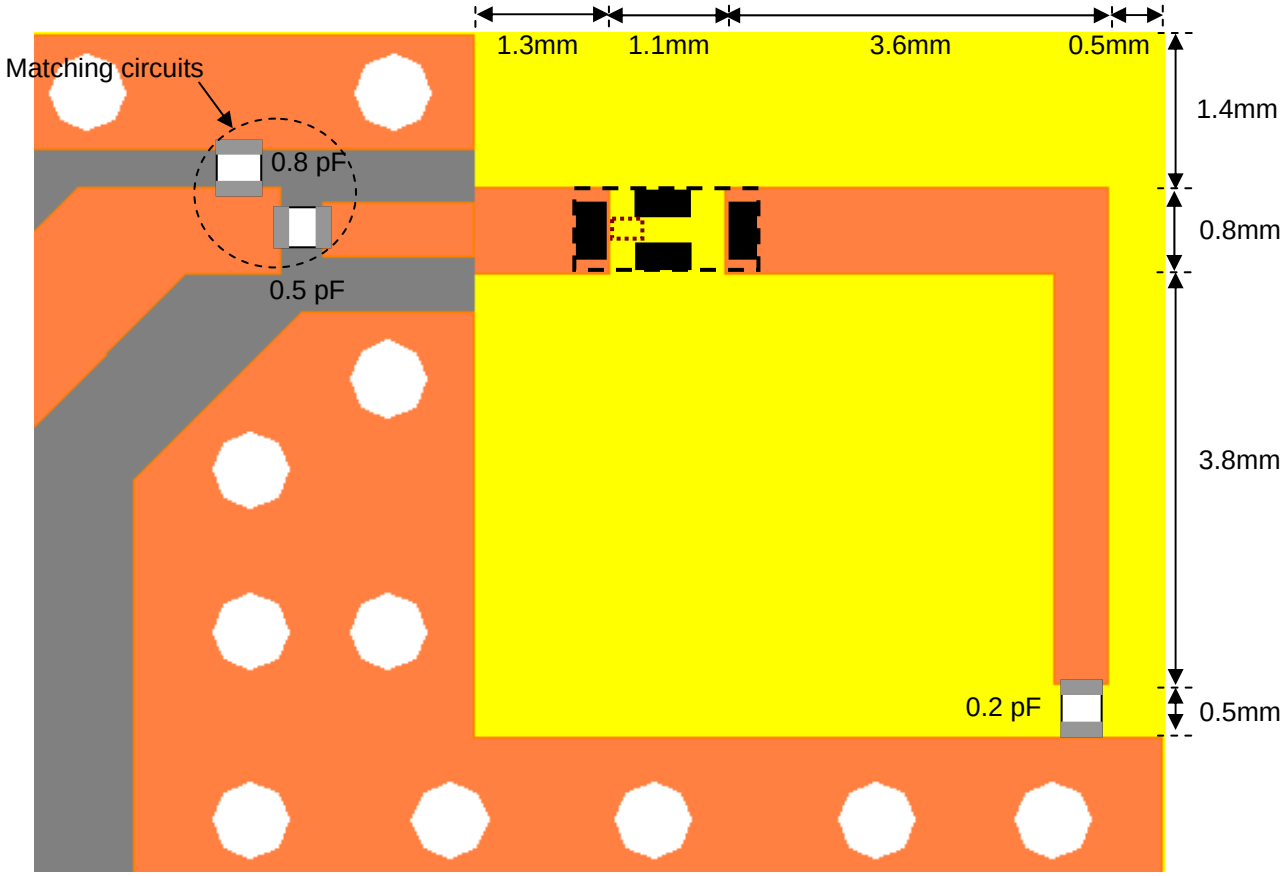


Typical Electrical Characteristics for Scenario#2 (T=25°C)

❖Test Board- Scenario#2



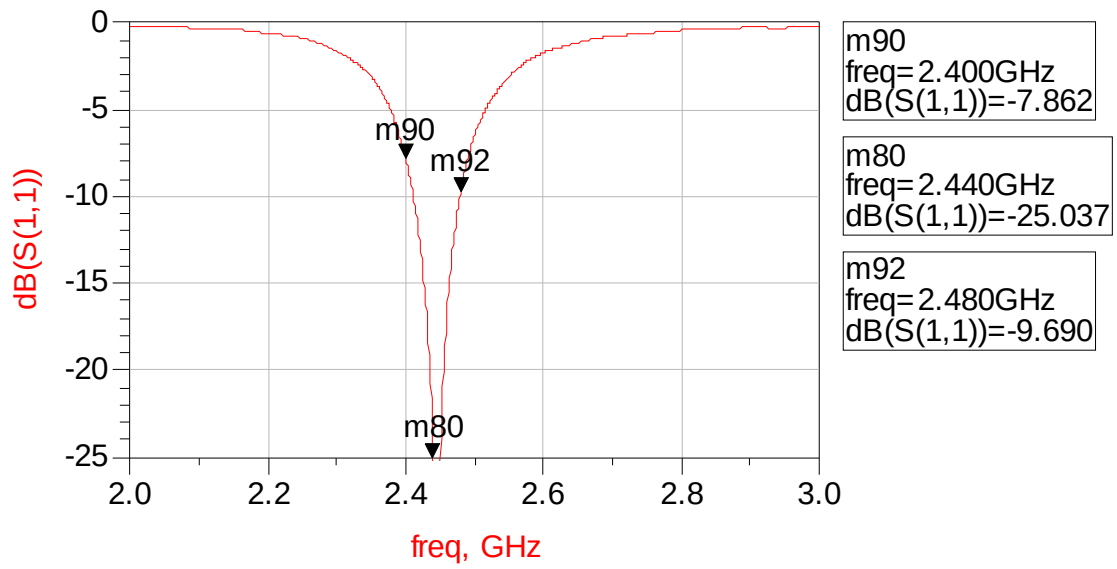
❖Antenna Footprint With matching- Scenario#2



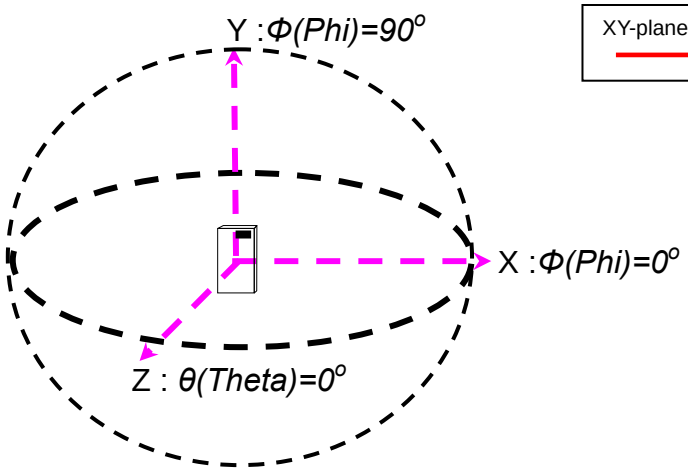
(Matching circuit and component values will be different, depending on PCB layout)

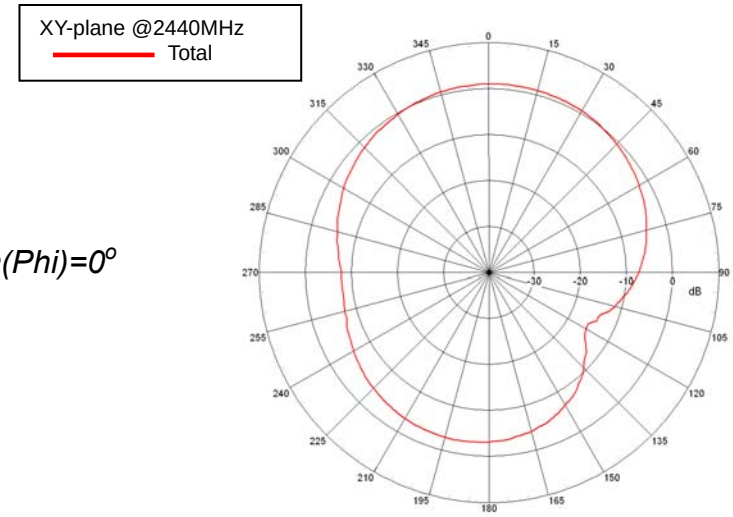
*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

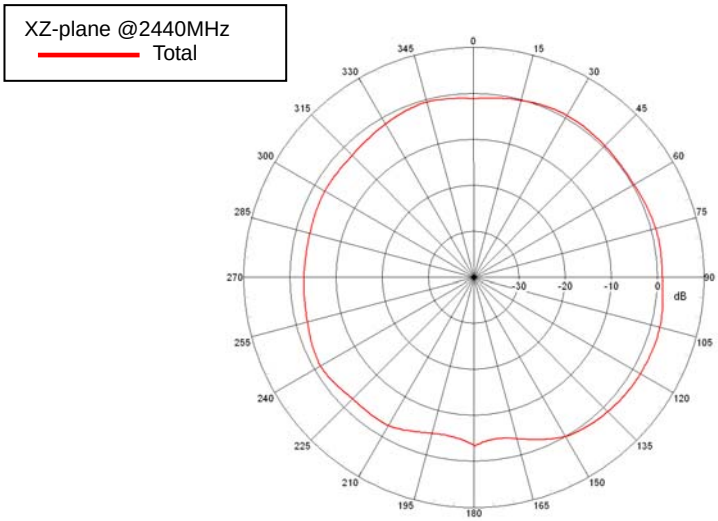
❖Return Loss (with matching)- Scenario#2

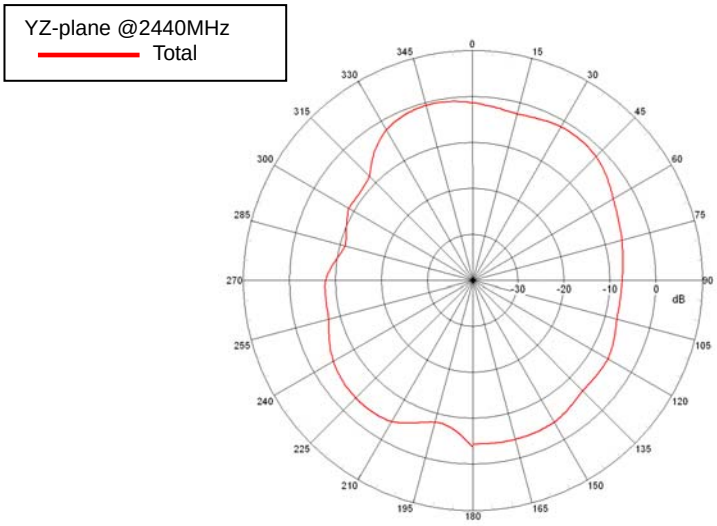


❖Radiation Patterns- Scenario#2 (Antenna Efficiency: 64 %)



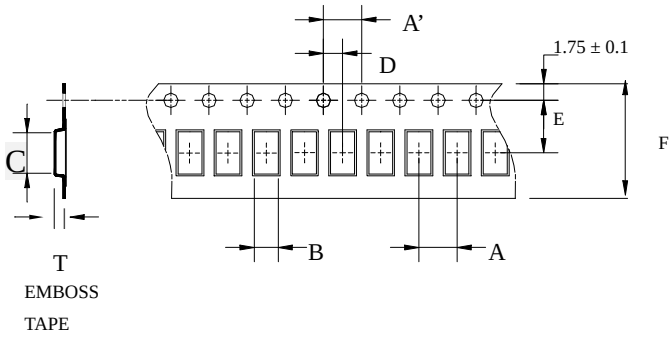






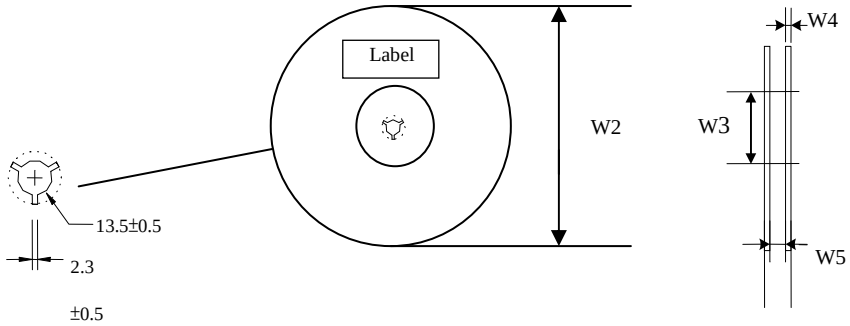
Taping Specifications

❖Tape & Reel Dimensions (Unit: mm) vs. Quantity (pcs)



Type	A	A'	B	C	D	E	F	T	Quantity/per reel	Tape material	Material No.
	4.0± 0.1	4.0± 0.1	2.4± 0.1	7.3± 0.1	2.0± 0.05	5.5± 0.1	12.0± 0.1	1.45± 0.1	1,000pcs	Plastic (Embossed)	1220104

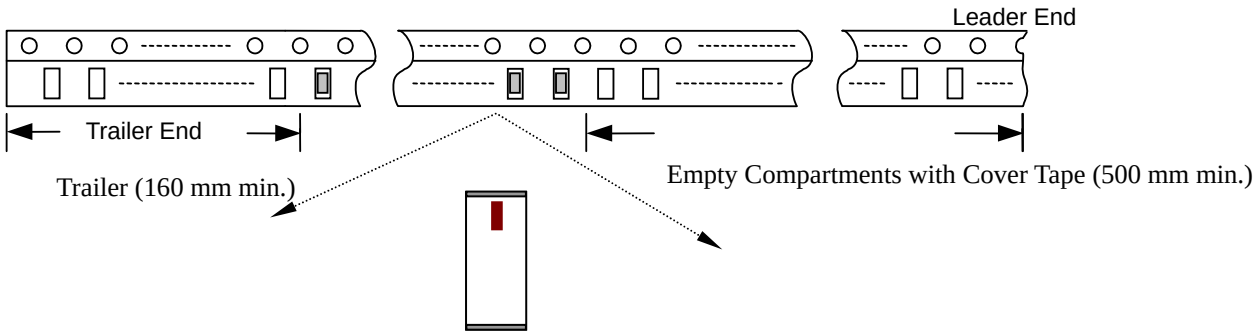
❖Reel Dimensions (Unit: mm)



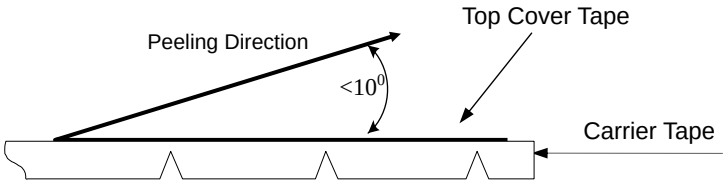
Label: Customer's Name,

Type	W2	W3	W4	W5	Material No.
	178±1	60±1	1.4±0.2	17±0.5	1220301

❖**Leader and Trailer Tape**



❖**Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300±10 mm/min .

❖**Storage Conditions**

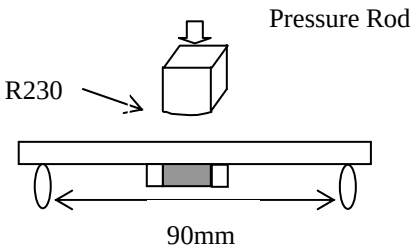
(1) Temperature: 5 ~35℃, relative humidity (RH): 45~75%.

(2) Non-corrosive environment

Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

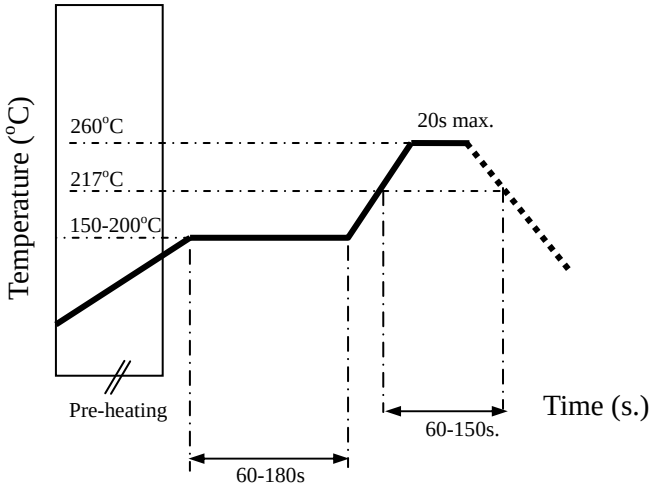
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: 120± 5 °C 2. Solder: 245± 5°C for 5± 1 sec
Soldering strength (Termination Adhesion)	1. 1kg minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. 2. Apply a bending force of 1mm deflection 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: 85± 2°C 2. Humidity: 90% ~ 95% RH 3. Duration: 1000±48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1：125 ± 5°C for 30 min step 2：- 40 ± 5°C for 30 min 2. No of cycles：100 3. Recovery:1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: -40°± 5 °C 2. Duration: 500 ±24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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Advanced Ceramic X Corp.
16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan
TEL:886-3-5987008 FAX:886-3-5987001
E-mail: acx@acxc.com.tw
http://www.acxc.com.tw